OUR onsemi REPRESENTATIVE FOR INFO THIS DEVICE IS NOT RE

OISC

THIS DEVICE IS NOT RECOMMENDED FOR NEW DESILE

OF RECO

OISC

THIS DEVICE IS NOT RECOMMENDED FOR NO





DATE 31 OCT 2006

NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL.

 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.70	0.80		
A1	0.00	0.05		
A3	0.20 REF			
b	0.20	0.30		
D	4.00 BSC			
D2	3.20	3.40		
Е	3.00 BSC			
E2	1.60	1.80		
е	0.50 BSC			
K	0.20			
	0.00	0.50		

L 0.30 0.50ef00ef00ef≸jTT2 1 Tf6.5669 4.2 TD0 Tc(L)TjTT4 1 Tf2.54



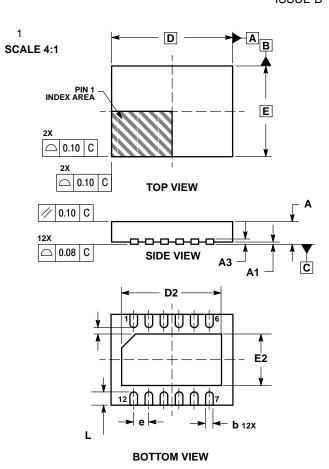
= Specific Device Code XXXXX = Assembly Location Α

= Year WW = Work Week

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part

Pb-Free indicator, "G" or microdot " ■", may or may not be present.



^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

